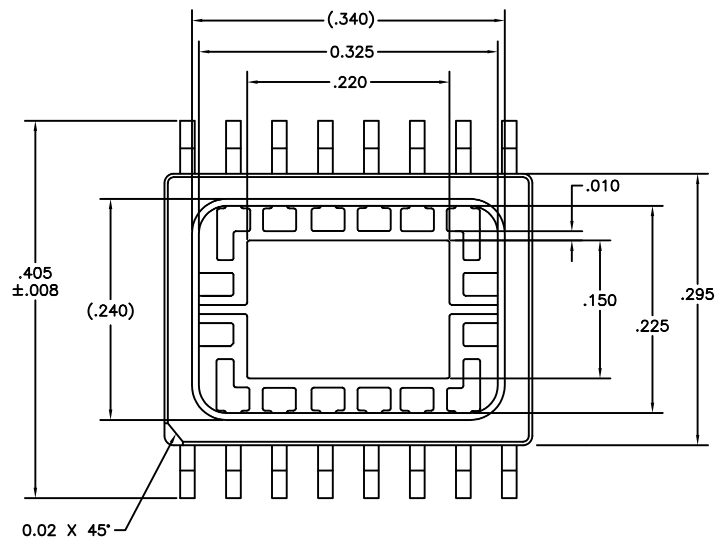
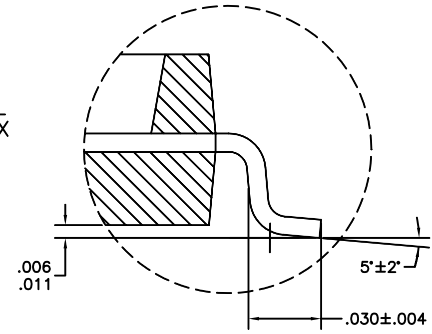
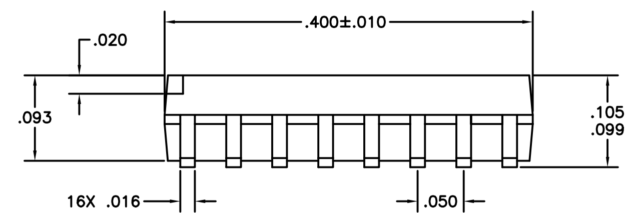
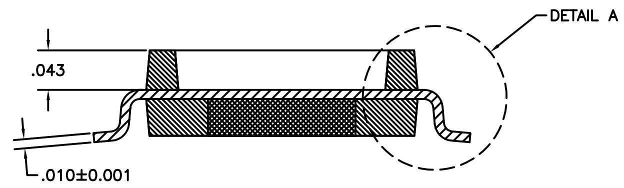
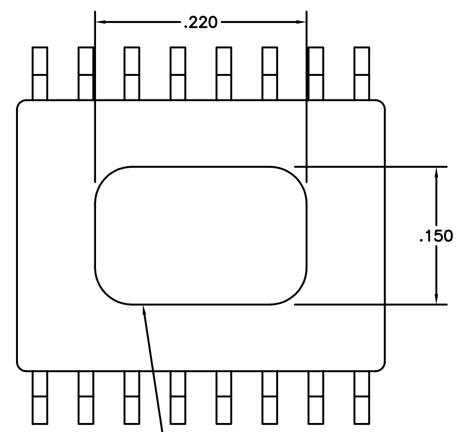
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10798	11/02/06	PRODUCTION RELEASE	D.BENANDO











NOTES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE
2. LEAD FRAME: COPPER, 194 FH.
3. LEAD FINISH: FULL Au PLATE.
4. FRAME THICKNESS: 0.0100±0.0003
5. DIE PAD: 0.220" x 0.150"
6. HEATSINK MATERIAL: COPPER, 194 FH.
7. HEATSINK SIZE: 0.210" x 0.140"±.006
8. JEDEC OTLINE: MS-013

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN **INCHES**
TOLERANCES ARE:
X.XX ± 0.01 X.XXXX ±---
X.XXX ± 0.005 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	C. CRUZ	DATE	11/02/06
APP BY	P. FLASKERUD	DATE	11/02/06
CUSTOMER	---		

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16 Lead 300 mils SOIC (Heat Enhanced) Open–Pak

SIZE	PART NO.	REV
A	SOIC300–16–OP–01H	3

SCALE NONE | CAD FILE SOIC300–16–OP–01H–R3.DWG | SHEET 1 OF 1

BORDER–AHI–1.DWG
REV 1 ECN 10598